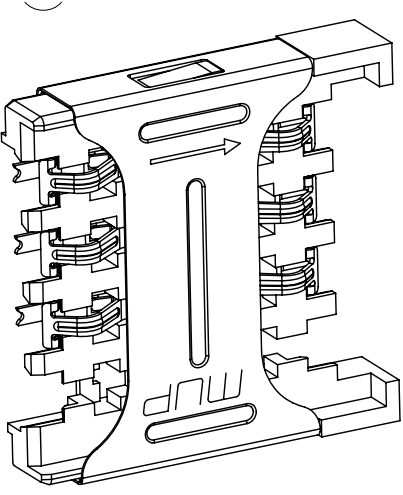
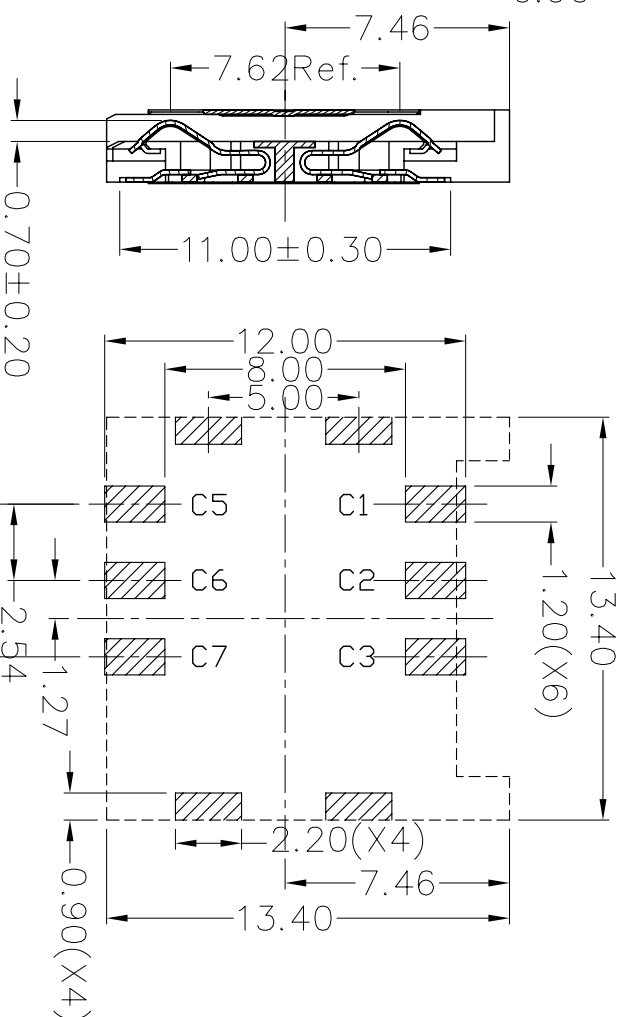
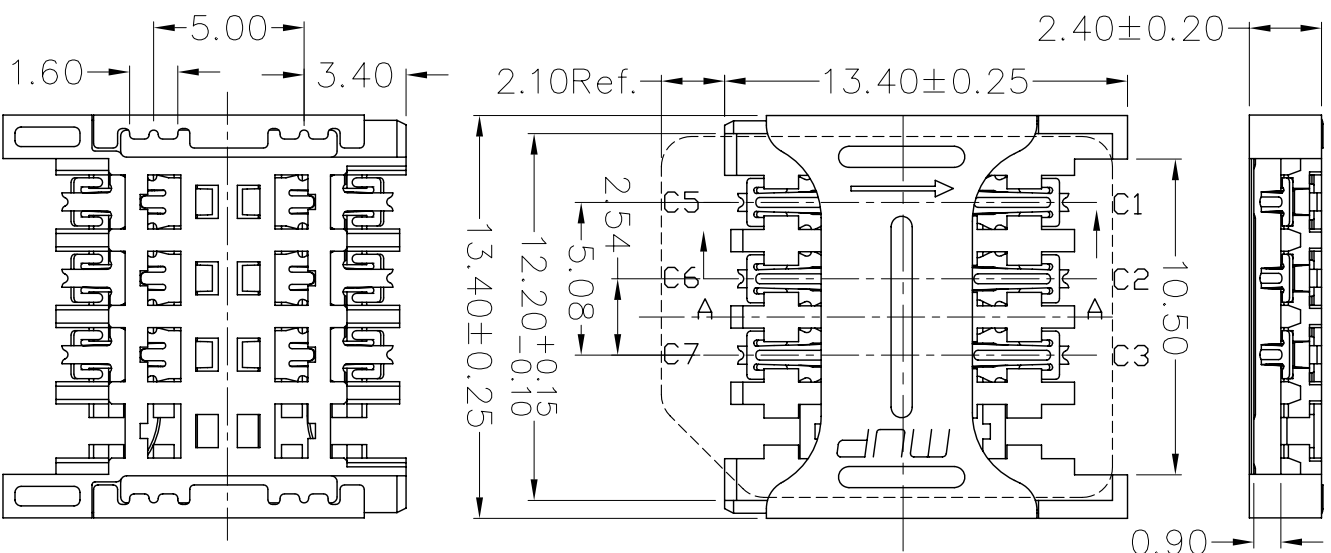


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



SECTION A-A

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 13.40LX13.40WX2.40H mm

Weight: Approx0.40±0.1g

Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical, 100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C, 30sec. Max

IR reflow: 250°C, 5sec. Max

Manual soldering: 370°C, 3sec. Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH

RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area: Gold plated
3	SHELL	1	Stainless steel	SMT area: Gold plated

X	±0.35	X'	±5°
X.X	±0.25	X.X'	±4°
X.XX	±0.15	X.XX'	±3°
X.XXX	±0.10	X.XXX'	±2°

PROJ.	UNIT	SCALE
	MM	1:1

CUSTOMER DRAWING	DRAWN	Mar.04.2011	DWG NO.:
	CHECKED	Seon Mar.04.2011	DWG-MUP-C790-001
	APPROVAL	Simon Mar.04.2011	SHEET 1/1
			REVISION X1

MUP MUP INDUSTRIAL CO.,LTD.

Micro-SIM Card Connector

MUP-C790

6Pin H=2.40 mm